



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20160830000
Change in TELEC ID No. for CC3100MOD and CC3200MOD Modules
Information Only**

Date: 8/31/2016
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**20160830000
Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC3200MODR1M2AMOBT	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20160830000	Notification Date:	Aug 31, 2016
Title:	Change in TELEC ID No. for CC3100MOD and CC3200MOD Modules		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
Texas Instruments Incorporated is announcing a change for the top side TELEC ID number on CC3100 and CC3200 Modules as follows:			
	TELEC I.D. No.		
Module No.	From	To	
CC3100	CC3100MOD: 001-A04798	CC3100MOD: 001-A08147	
CC3200	CC3200MOD: 001-A04799	CC3200MOD: 001-A08148	
Reason for Change:			
Update the TELEC ID number, such that the report reflects more accurate power spectrum density (PSD) measurements for all the 802.11 modulations.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this notification:			
None.			
Product Affected:			
CC3100MODR11MAMOBR	CC3200MODR1M2AMOBR		
CC3100MODR11MAMOBT	CC3200MODR1M2AMOBT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com